

2N5551HR

Hi-Rel NPN bipolar transistor 160 V - 0.5 A

Features

BV _{CEO}	160 V
I _C (max)	0.5 A
H _{FE} at 5 V - 10 mA	> 80
Operating temperature range	-65°C to +200°C

- Hi-Rel NPN bipolar transistor
- Linear gain characteristics
- ESCC qualified
- European preferred part list EPPL
- Radiation level: lot specific total dose contact marketing for specified level

Description

The 2N5551HR is a silicon planar epitaxial NPN transistor in TO-18, TO-39 and LCC-3 packages. It is specifically designed for aerospace Hi-Rel applications and ESCC qualified according to the 5201-019 specification. In case of conflict between this datasheet and ESCC detailed www.DataSheet4L com specification, the latter prevails.

TO-18	LCC-3				
TO-39					
	-				

Figure 1. Internal schematic diagram

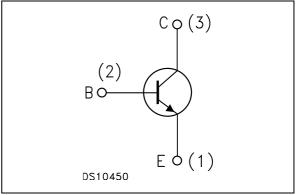


Table 1. Dev	vice summary					
Order codes	Packages	Lead finish	Marking	Туре	EPPL	Packaging
2N5551HR	TO-18	Gold Solder Dip	520101901 520101902	ESCC Flight		Strip pack
2N5551T1	TO-18	Gold	2N5551T1	Engineering model		Strip pack
SOC5551	LCC-3	Gold	SOC5551	Engineering model		Waffle pack
SOC5551HRB	LCC-3	Gold Solder Dip	520101904 520101905	ESCC Flight	Yes	Waffle pack
2N5551SHR	TO-39	Gold Solder Dip	520101906 520101907	ESCC Flight	Yes	Strip pack

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1 Electrical ratings

Symbol	Parameter	Value	Unit
-			
V _{CBO}	Collector-base voltage ($I_E = 0$)	180	V
V_{CEO}	Collector-emitter voltage ($I_B = 0$)	160	V
V_{EBO}	Emitter-base voltage ($I_{C} = 0$)	6	V
	Collector current		
I _C	for 2N5551HR	0.6	Α
for SOC5551HRB	for SOC5551HRB	0.5	Α
	Total dissipation at $T_{amb} \le 25 \text{ °C}$		
	for 2N5551HR	0.36	W
Р	for SOC5551HRB	0.36	W
P _{tot}	for SOC5551HRB ⁽¹⁾	0.58	W
	Total dissipation at $T_c \le 25 \text{ °C}$		
	for 2N5551HR	1.2	W
T _{stg}	Storage temperature	-65 to 200	°C
TJ	Max. operating junction temperature	200	°C

1. When mounted on a 8 x 10 x 0.6 mm ceramic substrate.

Symbol	Parameter	Value	Unit
R _{thJC}	Thermal resistance junction-case max	146	°C/W
R _{thJA}	Thermal resistance junction-ambient max	486	°C/W

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Table 4. Thermal data for SMD package

Symbol	Parameter	Value	Unit
Б	Thermal resistance junction-ambient max	486	°C/W
R _{thJA}	Thermal resistance junction-ambient ⁽¹⁾ max	302	°C/W

1. When mounted on a 8 x 10 x 0.6 mm ceramic substrate.



2 Electrical characteristics

 $T_{case} = 25 \ ^{\circ}C$ unless otherwise specified.

Table 5.							
Symbol	Parameter	Test co	nditions	Min.	Тур.	Max.	Unit
I _{CBO}	Collector-base cut-off current (I _E = 0)	V _{CB} = 120 V V _{CB} = 120 V	T _C = 150 °C			50 50	nA μA
I _{EBO}	Emitter-base cut-off current (I _C = 0)	V _{EB} = 4 V				50	nA
V _{(BR)CBO}	Collector-base breakdown voltage (I _E = 0)	I _C = 100 μΑ		180			V
V _{(BR)CEO} ⁽¹⁾	Collector-emitter breakdown voltage $(I_B = 0)$	I _C = 1 mA		160			V
V _{(BR)EBO}	Emitter-base breakdown voltage (I _C = 0)	Ι _Ε = 10 μΑ		6			v
V _{CE(sat)} ⁽¹⁾	Collector-emitter saturation voltage	l _C = 10 mA l _C = 50 mA	l _B = 1 mA l _B = 5 mA			0.15 0.2	V V
V _{BE(sat)} ⁽¹⁾	Base-emitter saturation voltage	I _C = 10 mA I _C = 50 mA	l _B = 1 mA l _B = 5 mA			1 1	V V
h _{FE} ⁽¹⁾	DC current gain	$I_{C} = 1 \text{ mA}$ $I_{C} = 10 \text{ mA}$ $I_{C} = 50 \text{ mA}$ $I_{C} = 10 \text{ mA}$ $T_{amb} = -55 \text{ °C}$	$V_{CE} = 5 V$	80 80 30 20		250	
h _{fe}	Small signal current gain	V _{CE} = 10 V f = 1 kHz	I _C = 1 mA	50		200	
h _{fe}	Small signal current gain	V _{CE} = 10 V f > 100 MHz	l _C = 10 mA	1			
C _{obo}	Output capacitance (I _E = 0)	V _{CB} = 10 V	f = 1 MHz			6	pF
C _{ebo}	Emitter-base capacitance (I _C = 0)	V _{EB} = 5 V	f = 1 MHz			20	pF

Table 5.	Electrical	characteristics
Table J.	LIECUICAI	characteristics

1. Pulsed duration = 300 μ s, duty cycle $\leq 1.5\%$

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3 Package mechanical data

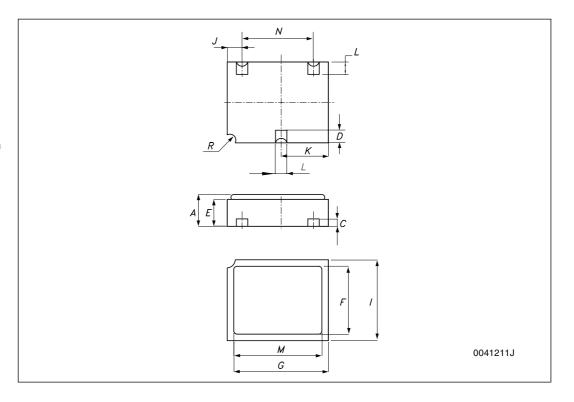
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

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DIM.		mm.	
	MIN.	ТҮР	MAX.
A	1.16		1.42
С	0.45	0.50	0.56
D		0.76	
E		1	
F	1.90		2.15
G	2.90		3.25
1	2.40		2.74
J	0.40	0.57	0.80
К	1.35	1.52	1.75
L		0.50	
М	2.40		2.65
N		1.90	
R		0.30	

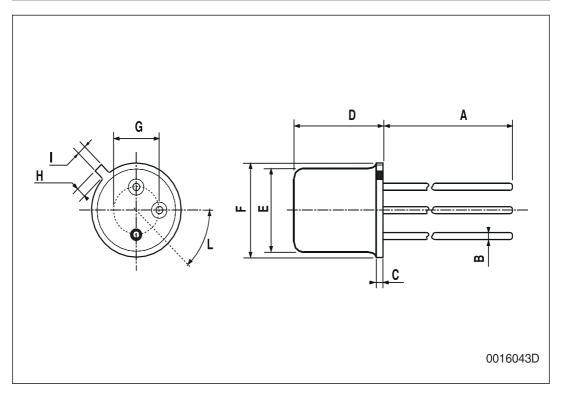
Ceramic Leadless Chip Carrier 3 mechanical data



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	TO-18 Mechanical data						
DIM.		mm					
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А		12.7			0.500		
В			0.49			0.019	
D			5.3			0.208	
E			4.9			0.193	
F			5.8			0.228	
G	2.54			0.100			
Н			1.2			0.047	
I			1.16			0.045	
L	45 [°]			45°			

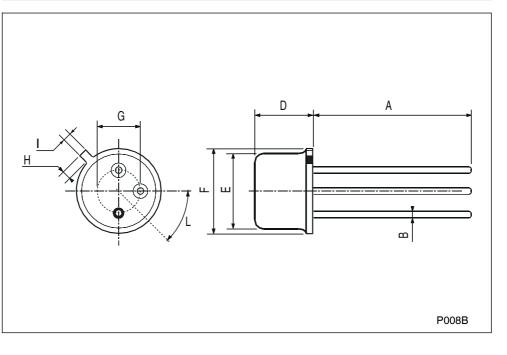


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TO-39 Mechanical data							
DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	12.7			0.500			
В			0.49			0.019	
D			6.6			0.260	
E			8.5			0.334	
F			9.4			0.370	
G	5.08			0.200			
н			1.2			0.047	
I			0.9			0.035	
L	45° (typ.)						



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4 Revision history

Table 6.Document revision history

Date	Revision	Changes
04-Jan-2010	1	Initial release

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